<u>REMARKS</u>

The rejections and comments of the Examiner set forth in the Office Action dated July 14, 2003 have been carefully reviewed by the Applicants.

Claims 1-8, and 10 are currently rejected under 35 U.S.C.

103(a) as being unpatentable over Yamada 1(JP 9064421) and Yamada

2 (JP 6177429) in view of Ishikawa (US 6046501). In response,

Claims 1-8, and 10 have been canceled and replaced by new Claims

11-18 that are patentably distinguished from Yamada 1, Yamada 2

and Ishikawa.

A first difference between the new Claims 11-18 and the cited combination is that the packaged semiconductor device of the present claimed invention comprises a semiconductor die having an exposed surface. Yamada 1, Yamada 2, and Ishikawa only teach a fully enclosed semiconductor die.

In the case of Yamada 1 and Yamada 2, the packaged device is a light emitting diode. The encapsulation of Yamada serves to support the die carrier and provide a lens material for the light

Serial No.: 09/468,249

emitting diode. As described by Yamada and shown in the drawings, the resin surrounds the LED.

In the case of Ishikawa, the RF-driven semiconductor device has one die surface mounted on a metal plate and the other covered by epoxy. No part of the die is exposed.

Another significant difference between cited references and the present claimed invention is that the leads of the present invention are formed in a single portion of the leadframe and have exposed coplanar mounting surfaces. In the present invention, the leads are essentially a single lead with multiple mounting surfaces.

In contrast, the leads of Ishikawa are electrically and mechanically distinct elements, each intended to carry a different signal or current. While Yamada teaches a cup for holding a die, the die lacks exposed coplanar mounting surfaces.

The combination of Yamada 1, Yamada 2 and Ishikawa fails to teach or suggest a packaged semiconductor device having an exposed die surface, and exposed mounting surfaces that are coplanar with

Serial No.: 09/468,249

the exposed die surface. In summary, Applicants assert that Claims 11-18 are in condition for allowance and earnestly solicit such action by the Examiner.

Please charge any additional fees or apply any credits to our PTO deposit account number: 23-0085.

Respectfully submitted,
WAGNER, MURABITO & HAO LLP

Date: Octob 14, 2003

Mehlin Dean Matthews

Registration Number: 46,127

WAGNER, MURABITO & HAO LLP Two North Market Street Third Floor San Jose, CA 95113

408-938-9060

Serial No.: 09/468,249